

METHOD AND APPARATUS FOR TRIMMING INTEGRATED CIRCUITS
ABSTRACT OF THE DISCLOSURE

A wafer containing integrated circuits having fuses which are selectively blown to trim circuit perimeters. The fuses are located adjacent scribe lanes, and fuse pads are located in the scribe lanes. The integrated circuits are trimmed by selectively energizing the fuse pads to blow selective fuses. When the integrated circuits are severed from the wafer, the fuse pads are severed from the integrated circuits.

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